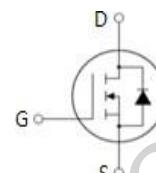
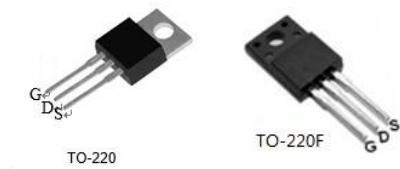


FEATURES

- Proprietary New Trench Technology
- Low Gate Charge Minimize Switching Loss
- Fast Recovery Body Diode

Applications

- High efficiency DC/DC Converters
- Synchronous Rectification
- UPS Inverter



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Value		Unit
		TO-220F	TO-220	
Drain-Source Voltage ($V_{GS} = 0\text{V}$)	V_{DSS}	80		V
Continuous Drain Current	I_D	85		A
Pulsed Drain Current (note1)	I_{DM}	340		A
Gate-Source Voltage	V_{GSS}	± 30		V
Single Pulse Avalanche Energy (note2)	E_{AS}	570		mJ
Single Pulse Avalanche Current (note1)	I_{AS}	36.6		A
Repetitive Avalanche Energy (note1)	E_{AR}	342		mJ
Power Dissipation ($T_C = 25^\circ\text{C}$)	P_D	55	43	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	$-55\text{~to~}+150$		°C

Thermal Resistance

Parameter	Symbol	Value		Unit
		TO-220F	TO-220	
Thermal Resistance, Junction-to-Case	R_{thJC}	5	4.2	K/W
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62.5	60	

Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Drain-to-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	80	--	--	V
Drain-to-Source Leakage Current	I_{DSS}	$V_{\text{DS}}=80\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	μA
		$V_{\text{DS}}=64\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	--	--	100	
Gate-to-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{TH})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2.0	--	4.0	V
Static Drain-to-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=40\text{A}$	--	9.5	12	$\text{m}\Omega$
Dynamic						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 25\text{V}, f = 1.0\text{MHz}$	--	2728	--	pF
Output Capacitance	C_{rss}		--	782	--	
Reverse Transfer Capacitance	C_{oss}		--	339	--	
Total Gate Charge	Q_g	$V_{\text{DD}}=40\text{V}, I_{\text{D}}=40\text{A}, V_{\text{GS}}=0 \text{ to } 10\text{V}$	--	164	--	nC
Gate-to-Source Charge	Q_{gs}		--	15	--	
Gate-to-Drain (Miller) Charge	Q_{gd}		--	71	--	
Turn-on Delay Time	$t_{\text{d}(\text{ON})}$	$V_{\text{DD}}=40\text{V}, I_{\text{D}}=10\text{A}, V_{\text{GS}}=10\text{V}, R_G=25\Omega$	--	50	--	nS
Rise Time	t_{rise}		--	106	--	
Turn-Off Delay Time	$t_{\text{d}(\text{OFF})}$		--	408	--	
Fall Time	t_{fall}		--	183	--	
Drain-Source Body Diode Characteristics						
Continuous Source Current (note2)	I_{SD}	Integral PN-diode in MOSFET	--	--	85	A
Pulsed Source Current (note2)	I_{SM}		--	--	340	
Diode Forward Voltage	V_{SD}	$I_{\text{S}}=75\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.2	V
Reverse recovery time	t_{rr}	$V_{\text{GS}}=0\text{V}, I_{\text{F}}=10\text{A}, d_{\text{I}}/\text{dt}=100\text{A}/\mu\text{s}$	--	100	--	ns
Reverse recovery charge	Q_{rr}		--	410	--	nC

Notes

- Repetitive Rating: Pulse width limited by maximum junction temperature
- $L=1\text{mH}, V_{\text{DD}} = 50\text{V}, R_G = 25 \Omega$, Starting $T_J = 25^\circ\text{C}$
- Pulse Test: Pulse width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1\%$

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Typical Output Characteristics

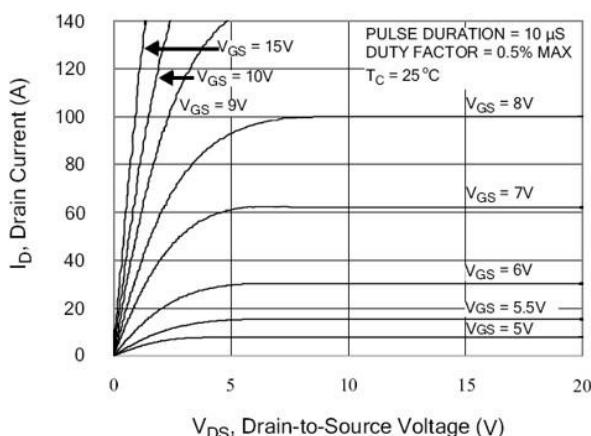


Figure 2. Maximum Power Dissipation vs Case Temperature

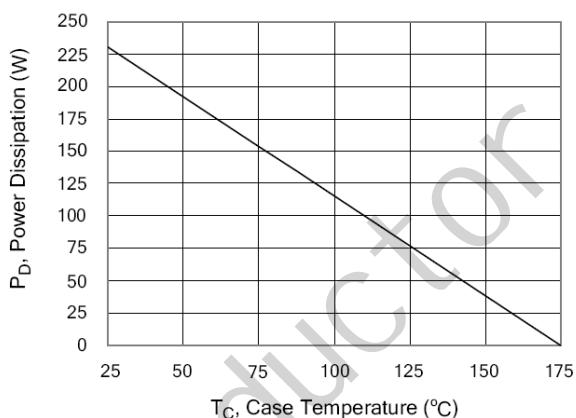


Figure 3. Maximum Continuous Drain Current vs Case Temperature

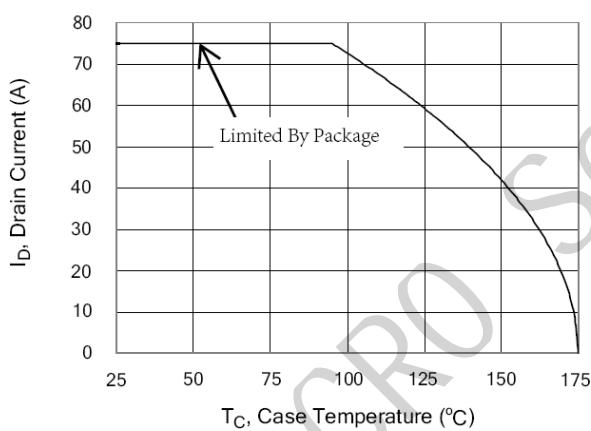


Figure 4. Typical Drain-to-Source ON Resistance vs Gate Voltage and Drain Current

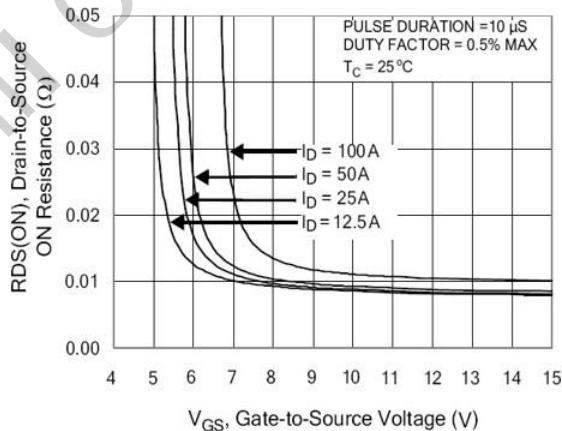


Figure 7. Typical Drain-to-Source ON Resistance vs Drain Current

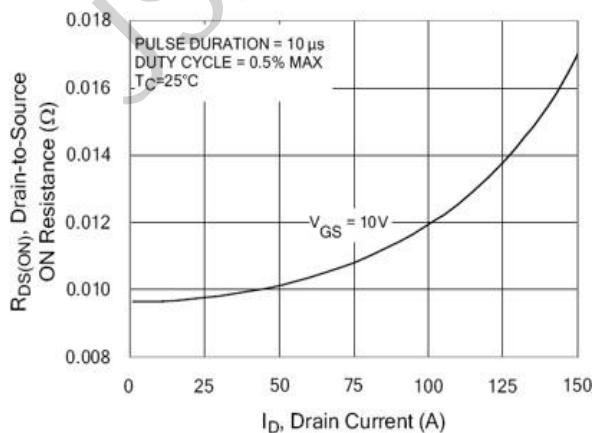
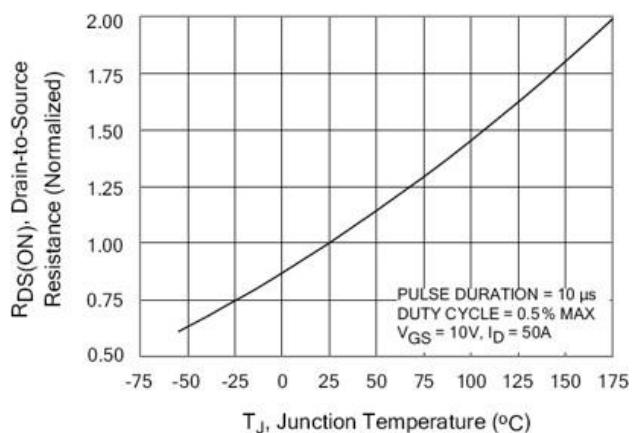


Figure 8. Typical Drain-to-Source ON Resistance vs Junction Temperature



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Capacitance

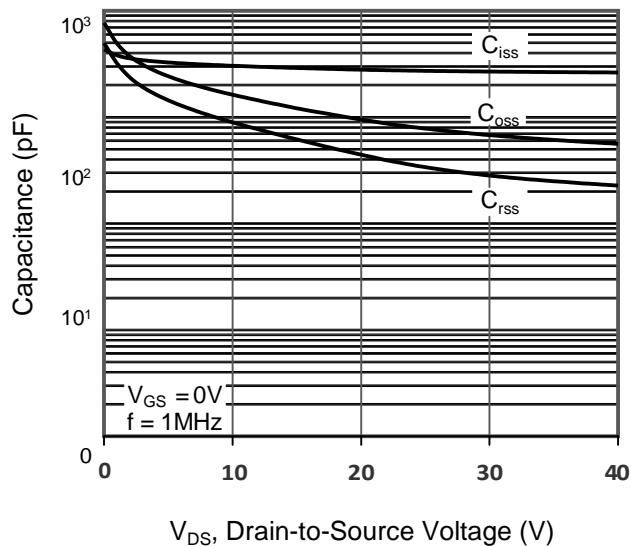
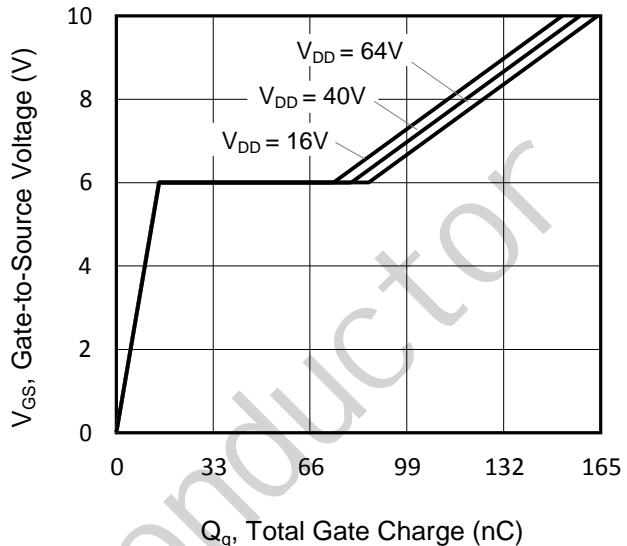
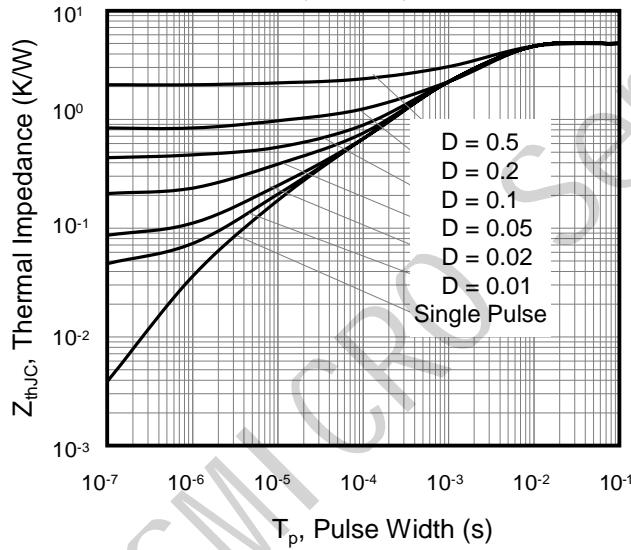


Figure 8. Gate Charge



**Figure 9. Transient Thermal Impedance
TO-251, TO-252, TO-220**



**Figure 10. Transient Thermal Impedance
TO-220F**

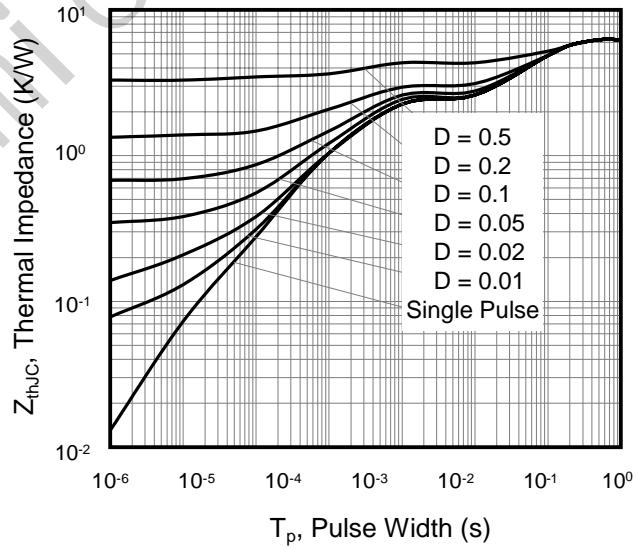
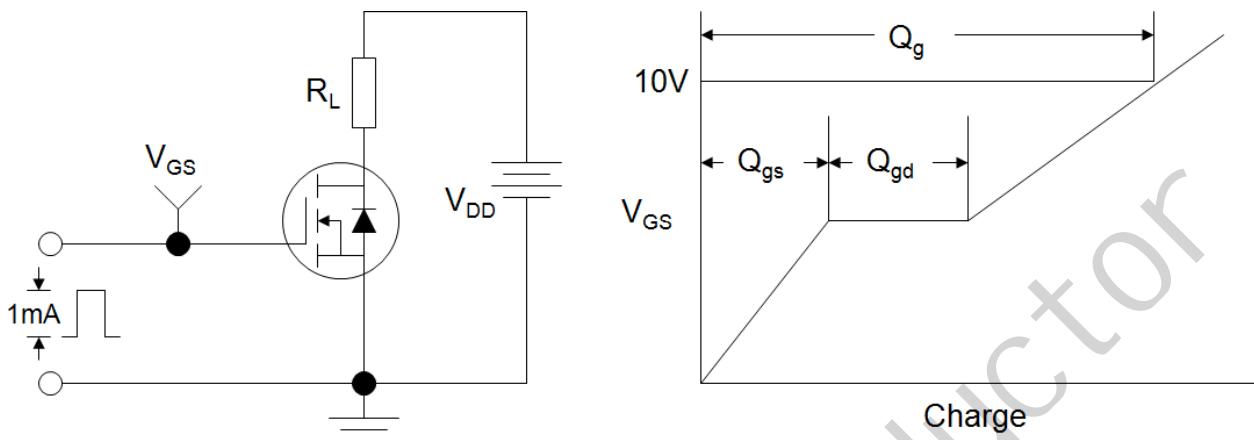
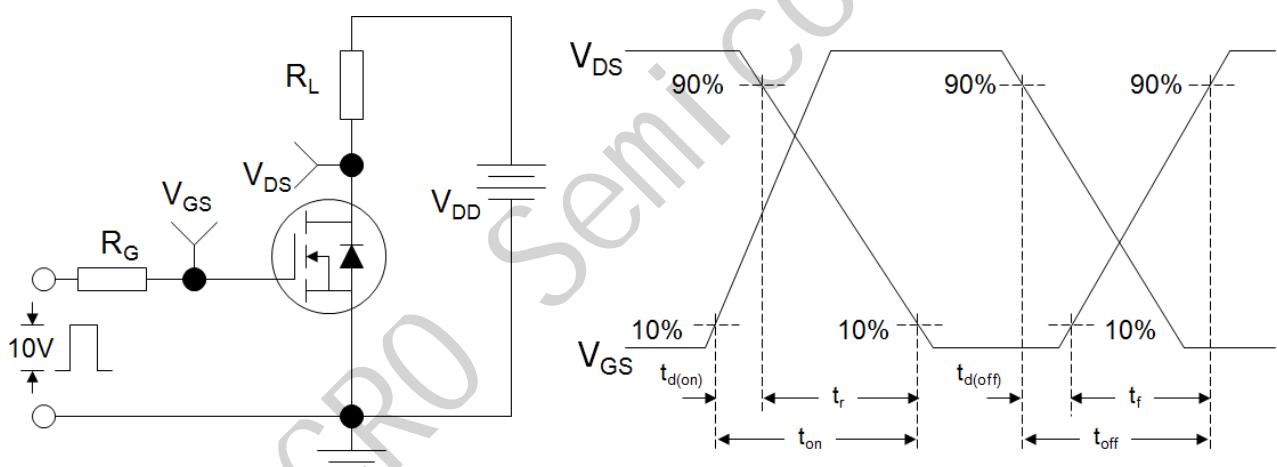
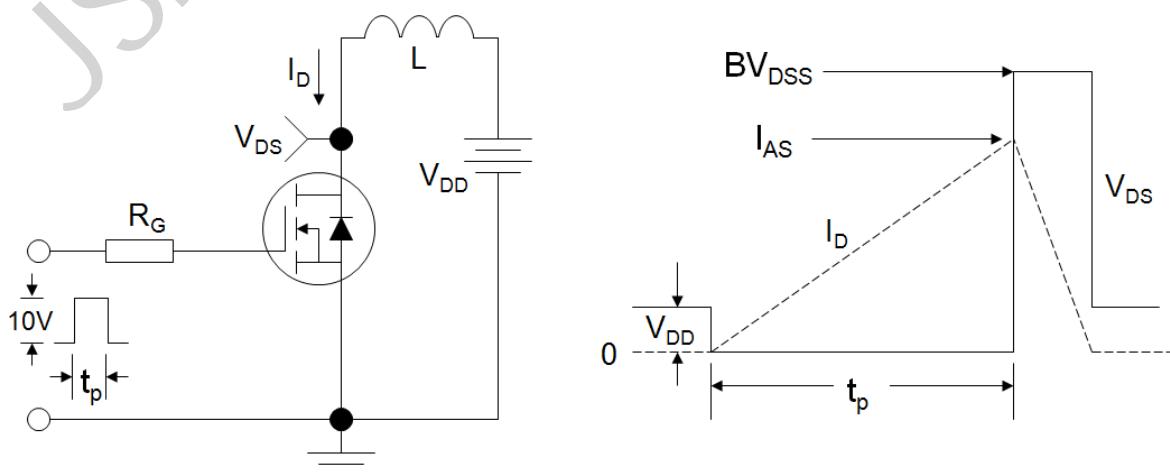
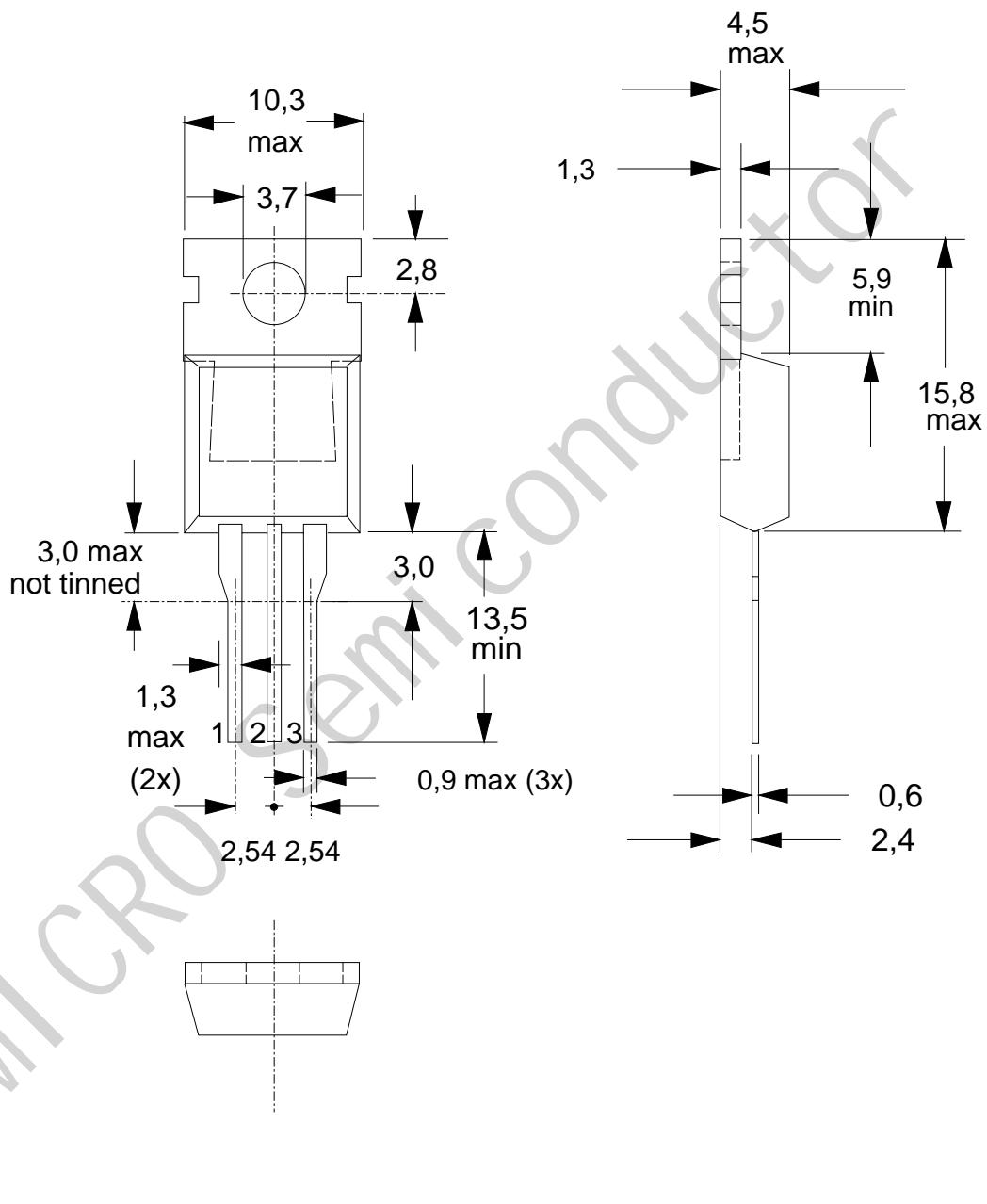


Figure A: Gate Charge Test Circuit and Waveform

Figure B: Resistive Switching Test Circuit and Waveform

Figure C: Unclamped Inductive Switching Test Circuit and Waveform


PACKAGE OUTLINE

TO-220

Dimensions in mm


TO-220F Package Dimensions

UNIT: mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A	9.80		10.60	D		2.54	
A1		7.00		D1	1.15		1.55
A2	2.90		3.40	D2	0.60		1.00
A3	9.10		9.90	D3	0.20		0.50
B1	15.40		16.40	E	2.24		2.84
B2	4.35		4.95	E1		0.70	
B3	6.00		7.40	E2		1.0×45°	
C	3.00		3.70	E3	0.35		0.65
C1	15.00		17.00	E4	2.30		3.30
C2	8.80		10.80	α (度)		30°	

